



Final Product Change Notification

202407004F02 : Migration of 88Q9098-A2-NYGA and 88W9098-A2-NYGC to UMC Fabrication, Change in Part Numbers

Note: This notice is NXP Company Proprietary.

Issue Date: Nov 22, 2024 **Effective Date:** May 30, 2025

Dear DigiKey Supplier Info PCNs,

Here is your personalized communication about an NXP notification.
For detailed information we invite you to view this notification online

Management summary

Migration of current 88Q9098-A2-NYGA and 88W9098-A2-NYGC product lines to new fabrication and assembly flows. The products addressed in this PCN will be migrated from TSMC-15 fabrication over to UMC-12A fabrication. These products will also be migrated from ASE-based package assembly over to SPIL-based package assembly. Due to change of assembly vendor from ASE to SPIL, New part numbers will be created to replace the original parts based on TSMC+ASE production flow.

Change Category

<input checked="" type="checkbox"/> Wafer Fab Process	<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input checked="" type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input checked="" type="checkbox"/> Firmware <input type="checkbox"/> Other				

Notification Overview

Description

1. Migration of current 88Q9098-A2-NYGA and 88W9098-A2-NYGC product lines to new fabrication and assembly flows. The product lines addressed in this PCN will be second-sourced from TSMC-15 (Taichung, Taiwan) fabrication by addition of UMC-12A (Tainan, Taiwan) fabrication.

2. Change of assembly subcontractor from ASE to SPIL for the 88Q9098-A2-NYGA and 88W9098-A2-NYGC variants. These product lines will be migrated to new Part Numbers due to differences in package-corner shape between ASE-QFN and SPIL-QFN packages.

3. Planned Fabrication + Assembly + Final-Test flows are as follows:

Currently qualified flows:

88Q9098-A2-NYGA, 88W9098-A2-NYGC:

- o TSMC-15 fabrication + ASE assembly + ASE-K final test
- o TSMC-15 fabrication + ASE assembly + ASE-CL final test
- o TSMC-15 fabrication + ASE assembly + NXP-ATKH final test

New production flows planned:

88Q9098-A2-NYGA, 88W9098-A2-NYGC:

- o These variants will be migrated to new part numbers due to assembly vendor change – see included attachment for more details:
- o 88Q9098-A2-NYGA --> 88Q9098-A2-NYKA
- o 88W9098-A2-NYGC --> 88W9098-A2-NYKC

The 88Q9098-A2-NYKA and 88W9098-A2-NYKC will be manufactured with the following production flows – all below production flows have already been qualified with the AW690HNK automotive product:

- o UMC-12A fabrication + SPIL assembly + SPIL-H final test
- o UMC-12A fabrication + SPIL assembly + ASEK-CL final test
- o UMC-12A fabrication + SPIL assembly + NXP-ATKH final test
- o TSMC-15 fabrication + SPIL assembly + SPIL-H final test
- o TSMC-15 fabrication + SPIL assembly + ASEK-CL final test
- o TSMC-15 fabrication + SPIL assembly + NXP-ATKH final test

4. All final test sites will use identical ATE vendor equipment model, identical final test program, and identical ATE / FT-program configuration as the current TSMC-based product variants. Final test implementation into production will be cross-correlated across all sites to ensure manufacturing and quality equivalency.

5. 4 All customers will need to be prepared to migrate to the new replacement part numbers by 30-May-2025. Please see attached overview for additional details.

6. Key product milestones and sample / production availability are as follows:

- 88Q9098 / 88W9098 Datasheet update: Now
- Qualification reports: Now
- Customer Qualification Samples: 22-Dec-2024
- 88Q9098-A2-NYKA PPAP: 06-Dec-2024
- Required customer conversion readiness (all variants): 30-May-2025

Reason

Migration of fabrication and assembly flows is being done to ensure robust supply throughout the life of the 88Q9098 and 88W9098 programs.

Identification of Affected Products

- Top Side Marking
- Packing Labels
- Replacement part number created for certain variants, please see included attachments for details

Product Availability

Sample Information

Samples are available from Dec 22, 2024

Production

Planned first shipment May 30, 2025

Anticipated Impact on Form, Fit, Function, Reliability or Quality

Minor change in package corner shape - please see included attachments for details. Form, fit, and mechanical specification is unchanged otherwise.

Data Sheet Revision

A new data sheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: view online

Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Dec 22, 2024.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Trent Bartow
e-mail address	trent.bartow@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2024 NXP Semiconductors. All rights reserved.

12NC	Orderable Part Number	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
935419183528	88W9098-A2-NYGC/MP	88W9098-A2-NYGC/A	MVL	H(V)MRQFN148P	SOT2111-1	CQS	No	BLT7
935419183557	88W9098-A2-NYGC/AK	88W9098-A2-NYGC/A	MVL	H(V)MRQFN148P	SOT2111-1	CQS	No	BLT7
935419204528	88Q9098-A2-NYGA/MP	88Q9098-A2-NYGA/A	MVL	H(V)MRQFN148P	SOT2111-1	RFS	No	BLT7
935419204557	88Q9098-A2-NYGA/AK	88Q9098-A2-NYGA/A	MVL	H(V)MRQFN148P	SOT2111-1	RFS	No	BLT7
935432106528	AW690HNN/A2AMP	AW690HNN/A2A	Seahawk	H(V)MRQFN148	SOT2111-2	RFS	No	BLT7
935432106557	AW690HNN/A2AK	AW690HNN/A2A	Seahawk	H(V)MRQFN148	SOT2111-2	RFS	No	BLT7
935445176557	AW690HNN/A2WK	AW690HNN/A2W	Seahawk	H(V)MRQFN148	SOT2111-2	CQS	No	BLT7